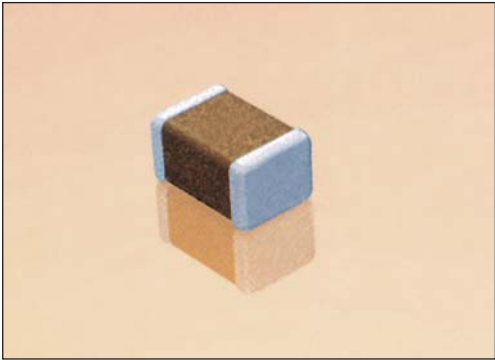


X5R Dielectric

General Specifications



GENERAL DESCRIPTION

- General Purpose Dielectric for Ceramic Capacitors
- EIA Class II Dielectric
- Temperature variation of capacitance is within $\pm 15\%$ from -55°C to $+85^{\circ}\text{C}$
- Well suited for decoupling and filtering applications
- Available in High Capacitance values (up to $100\mu\text{F}$)

PART NUMBER (see page 2 for complete part number explanation)

1210

Size
(L" x W")

4

Voltage
4 = 4V
6 = 6.3V
Z = 10V
Y = 16V
3 = 25V
D = 35V
5 = 50V

D

Dielectric
D = X5R

107

Capacitance Code (In pF)
2 Sig. Digits +
Number of
Zeros

M

Capacitance Tolerance
K = $\pm 10\%$
M = $\pm 20\%$

A

Failure Rate
A = N/A

T

Terminations
T = Plated Ni
and Sn

2

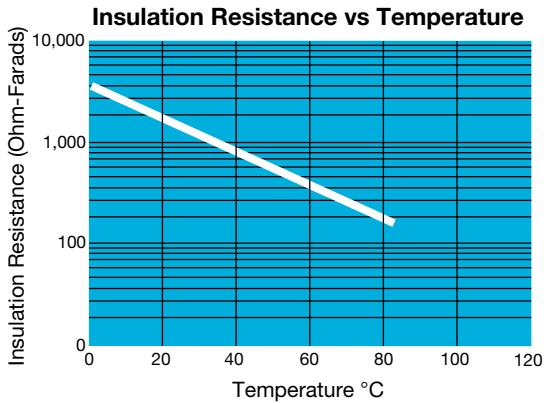
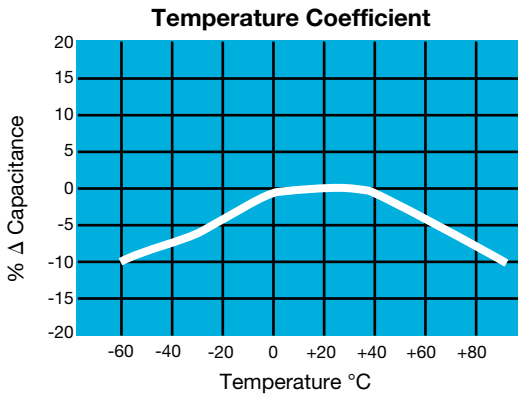
Packaging
2 = 7" Reel
4 = 13" Reel
7 = Bulk Cass.
9 = Bulk

A

Special Code
A = Std.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.
Contact factory for non-specified capacitance values.

TYPICAL ELECTRICAL CHARACTERISTICS



X5R Dielectric



Specifications and Test Methods

Parameter/Test		X5R Specification Limits	Measuring Conditions	
Operating Temperature Range		-55°C to +85°C	Temperature Cycle Chamber	
Capacitance		Within specified tolerance	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 µF, 0.5Vrms @ 120Hz	
Dissipation Factor		≤ 2.5% for ≥ 50V DC rating ≤ 3.0% for 25V DC rating ≤ 12.5% Max. for 16V DC rating and lower Contact Factory for DF by PN		
Insulation Resistance		10,000MΩ or 500MΩ - µF, whichever is less	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity	
Dielectric Strength		No breakdown or visual defects	Charge device with 300% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)	
Resistance to Flexure Stresses	Appearance	No defects	Deflection: 2mm Test Time: 30 seconds 	
	Capacitance Variation	≤ ±12%		
	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	≥ Initial Value x 0.3		
Solderability		≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic solder at 230 ± 5°C for 5.0 ± 0.5 seconds	
Resistance to Solder Heat	Appearance	No defects, <25% leaching of either end terminal	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.	
	Capacitance Variation	≤ ±7.5%		
	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	Meets Initial Values (As Above)		
	Dielectric Strength	Meets Initial Values (As Above)		
Thermal Shock	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes
	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ± 2 hours at room temperature	
	Load Life		Meets Initial Values (As Above)	Charge device with 1.5X rated voltage in test chamber set at 85°C ± 2°C for 1000 hours (+48, -0). Note: Contact factory for *optional specification part numbers that are tested at < 1.5X rated voltage.
Load Humidity	Appearance	No visual defects	Remove from test chamber and stabilize at room temperature for 24 ± 2 hours before measuring. Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied. Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring.	
	Capacitance Variation	≤ ±12.5%		
	Dissipation Factor	≤ Initial Value x 2.0 (See Above)		
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)		
	Dielectric Strength	Meets Initial Values (As Above)		

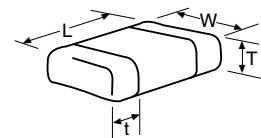
X5R Dielectric

Capacitance Range



PREFERRED SIZES ARE SHADED

SIZE	0101*	0201	0402	0603	0805	1206	1210	1812
Soldering	Reflow Only	Reflow Only	Reflow/Wave	Reflow/Wave	Reflow/Wave	Reflow/Wave	Reflow Only	Reflow Only
Packaging	Paper/Embossed	All Paper	All Paper	All Paper	Paper/Embossed	Paper/Embossed	Paper/Embossed	All Embossed
(L) Length	mm (in.)	0.40 ± 0.02 (0.016 ± 0.0008)	0.60 ± 0.03 (0.024 ± 0.001)	1.00 ± 0.10 (0.040 ± 0.004)	1.60 ± 0.15 (0.063 ± 0.006)	2.01 ± 0.20 (0.079 ± 0.008)	3.20 ± 0.20 (0.126 ± 0.008)	4.50 ± 0.30 (0.177 ± 0.012)
(W) Width	mm (in.)	0.20 ± 0.02 (0.008 ± 0.0008)	0.30 ± 0.03 (0.011 ± 0.001)	0.50 ± 0.10 (0.020 ± 0.004)	0.81 ± 0.15 (0.032 ± 0.006)	1.25 ± 0.20 (0.049 ± 0.008)	1.60 ± 0.20 (0.063 ± 0.008)	3.20 ± 0.20 (0.126 ± 0.008)
(t) Terminal	mm (in.)	0.10 ± 0.04 (0.004 ± 0.016)	0.15 ± 0.05 (0.006 ± 0.002)	0.25 ± 0.15 (0.010 ± 0.006)	0.35 ± 0.15 (0.014 ± 0.006)	0.50 ± 0.25 (0.020 ± 0.010)	0.50 ± 0.25 (0.020 ± 0.010)	0.61 ± 0.36 (0.024 ± 0.014)
WVDC	6.3 10	4 6.3 10 16 25	4 6.3 10 16 25 50	4 6.3 10 16 25 35 50	6.3 10 16 25 35 50	6.3 10 16 25 35 50	6.3 10 16 25 35 50 100	4 6.3 10 16 25 35 50
Cap (pF)	100	B	A	C				
	150	B	A					
	220	B	A					
	330	B	A	C				
	470	B	A	C				
	680	B	A	C				
	1000	B	A	C				
	1500	B	A	C				
	2200	B	A	C				
	3300	B	A	C				
	4700	B	A	C	G			
	6800	B	A	C	G			
Cap (µF)	0.010	B	A	C	G			
	0.015	B	A	C	G			
	0.022	B	A*	C	G	N		
	0.033	B	A*	C	G	N		
	0.047	B	A*	C	G	N		
	0.068	B	A*	C	G	N		
	0.10	B	A*	C	G	N		
	0.15		A*	C	G	N		
	0.22		A*	C*	G	N	Q	
	0.33		A*	C*	G	N		
	0.47		A*	C*	G	N	Q	X
	0.68		A*	C*	G	N	Q	X
	1.0		A*	C*	G	N	Q	X
	1.5		A*	C*	G	N	Q	X
	2.2		A*	C*	G	N	Q	X
	3.3			E*	J*	N	Q	Z
	4.7			E*	J*	N	Q	Z
	10				J*	N	Q	Z
	22				K	N*	Q*	Z*
	47					N*	Q*	Z*
	100					N*	Q*	Z*
WVDC	6.3 10	4 6.3 10 16 25	4 6.3 10 16 25 50	4 6.3 10 16 25 35 50	6.3 10 16 25 35 50	6.3 10 16 25 35 50	6.3 10 16 25 35 50 100	4 6.3 10 16 25 35 50



Letter	A	B	C	E	G	J	K	M	N	P	Q	X	Y	Z
Max. Thickness	0.33 (0.013)	0.22 (0.009)	0.56 (0.022)	0.71 (0.028)	0.90 (0.035)	0.94 (0.037)	1.02 (0.040)	1.27 (0.050)	1.40 (0.055)	1.52 (0.060)	1.78 (0.070)	2.29 (0.090)	2.54 (0.100)	2.79 (0.110)
	PAPER						EMBOSED							

- = Under Development
- = *Optional Specifications – Contact factory

NOTE: Contact factory for non-specified capacitance values

*EIA 01005

